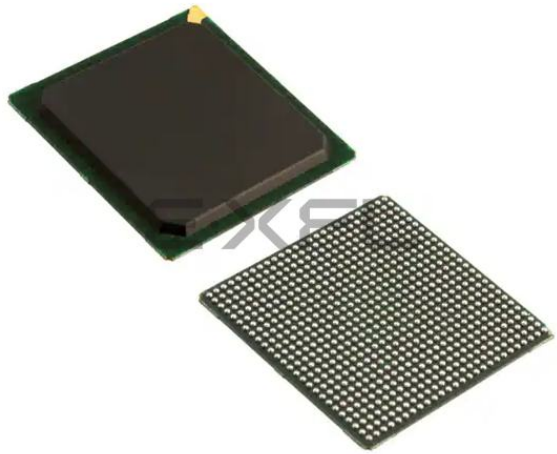

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	4848
Number of Logic Elements/Cells	43632
Total RAM Bits	3538944
Number of I/O	416
Number of Gates	-
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	676-BGA
Supplier Device Package	676-FBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc2vp40-6fgg676c

Output Swing and Emphasis

The output swing and emphasis levels are fully programmable. Each is controlled via attributes at configuration, and can be modified via the PMA attribute programming bus.

The programmable output swing control can adjust the differential peak-to-peak output level between 200 mV and 1600 mV.

With emphasis, the differential voltage swing is boosted to create a stronger rising or falling waveform. This method compensates for high frequency loss in the transmission media that would otherwise limit the magnitude of this waveform. Lossy transmission lines cause the dissipation of electrical energy. This emphasis technique extends the distance that signals can be driven down lossy line media and increases the signal-to-noise ratio at the receiver.

Emphasis can be described from two perspectives, additive to the smaller voltage (V_{SM}) (pre-emphasis) or subtractive from the larger voltage (V_{LG}) (de-emphasis). The resulting benefits in compensating for channel loss are identical. It is simply a relative way of specifying the effect at the transmitter.

The equations for calculating pre-emphasis as a percentage and dB are as follows:

$$\text{Pre-Emphasis}_{\%} = ((V_{LG}-V_{SM}) / V_{SM}) \times 100$$
$$\text{Pre-Emphasis}_{dB} = 20 \log(V_{LG}/V_{SM})$$

The equations for calculating de-emphasis as a percentage and dB are as follows:

$$\text{De-Emphasis}_{\%} = (V_{LG} - V_{SM}) / V_{LG}) \times 100$$
$$\text{De-Emphasis}_{dB} = 20 \log(V_{SM}/V_{LG})$$

The pre-emphasis amount can be programmed in discrete steps between 0% and 500%. The de-emphasis amount can be programmed in discrete steps between 0% and 83%.

Serializer

The serializer multiplies the reference frequency provided on REFCLK by 10, 16, 20, 32, or 40, depending on the operation mode. The multiplication of the clock is achieved by using an embedded PLL.

Data is converted from parallel to serial format and transmitted on the TXP and TXN differential outputs. The electrical connection of TXP and TXN can be interchanged through configuration. This option can be controlled by an input (TXPOLARITY) at the FPGA transmitter interface.

Deserializer

Synchronous serial data reception is facilitated by a clock and data recovery (CDR) circuit. This circuit uses a fully monolithic Phase Lock Loop (PLL), which does not require any external components. The CDR circuit extracts both phase and frequency from the incoming data stream.

The derived clock, RXRECCLK, is generated and locked to as long as it remains within the specified component range. This clock is presented to the FPGA fabric at $^1/_{10}$, $^1/_{16}$, $^1/_{20}$, $^1/_{32}$, or $^1/_{40}$ the incoming data rate depending on the operating mode.

A sufficient number of transitions must be present in the data stream for CDR to work properly. The CDR circuit is guaranteed to work with 8B/10B and 64B/66B encoding. Further, CDR requires approximately 5,000 transitions upon power-up to guarantee locking to the incoming data rate. Once lock is achieved, up to 75 missing transitions can be tolerated before lock to the incoming data stream is lost.

Another feature of CDR is its ability to accept an external precision reference clock, REFCLK, which either acts to clock incoming data or to assist in synchronizing the derived RXRECCLK.

For further clarity, the TXUSRCLK is used to clock data from the FPGA fabric to the TX FIFO. The FIFO depth accounts for the slight phase difference between these two clocks. If the clocks are locked in frequency, then the FIFO acts much like a pass-through buffer.

The receiver can be configured to reverse the RXP and RXN inputs. This can be useful in the event that printed circuit board traces have been reversed.

Receiver Lock Control

The CDR circuits will lock to the reference clock automatically if the data is not present. For proper operation, the frequency of the reference clock must be within ±100 ppm of the nominal frequency.

During normal operation, the receiver PLL automatically locks to incoming data (when present) or to the local reference clock (when data is not present). This is the default configuration for all primitives. This function can be overridden via the PMARXLOCKSEL port

When receive PLL lock is forced to the local reference, phase information from the incoming data stream is ignored. Data continues to be sampled, but synchronous to the local reference rather than relative to edges in the data stream.

Receive Equalization

In addition to transmit emphasis, the RocketIO X MGT provides a programmable active receive equalization feature to further compensate the effects of channel attenuation at high frequencies.

By adjusting RXFER, the right amount of equalization can be added to reverse the signal degradation caused by a printed circuit board, a backplane, or a line/switch card. RXFER can be set through software configuration or the PMA Attribute Bus.

Receiver Termination

On-chip termination is provided at the receiver, eliminating the need for external termination. The receiver termination supply (V_{TRX}) is the center tap of differential termination to

- Single-cycle and multi-cycle mode option for I-side and D-side interfaces
- Single cycle = one CPU clock cycle; multi-cycle = minimum of two and maximum of eight CPU clock cycles
- FPGA configurable DCR addresses within DSOCM and ISOCM.
- Independent 16 MB logical memory space available within PPC405 memory map for each of the DSOCM and ISOCM. The number of block RAMs in the device might limit the maximum amount of OCM supported.
- Maximum of 64K and 128K bytes addressable from DSOCM and ISOCM interfaces, respectively, using address outputs from OCM directly without additional decoding logic.

Data-Side OCM (DSOCM)

- 32-bit Data Read bus and 32-bit Data Write bus
- Byte write access to DSBRAM support
- Second port of dual port DSBRAM is available to read/write from an FPGA interface
- 22-bit address to DSBRAM port
- 8-bit DCR Registers: DSCNTL, DSARC
- Three alternatives to write into DSBRAM: BRAM initialization, CPU, FPGA H/W using second port

Instruction-Side OCM (ISOCM)

The ISOCM interface contains a 64-bit read only port, for instruction fetches, and a 32-bit write only port, to initialize or test the ISBRAM. When implementing the read only port, the user must deassert the write port inputs. The preferred method of initializing the ISBRAM is through the configuration bitstream.

- 64-bit Data Read Only bus (two instructions per cycle)
- 32-bit Data Write Only bus (through DCR)
- Separate 21-bit address to ISBRAM
- 8-bit DCR Registers: ISCNTL, ISARC
- 32-bit DCR Registers: ISINIT, ISFILL
- Two alternatives to write into ISBRAM: BRAM initialization, DCR and write instruction

Clock/Control Interface Logic

The clock/control interface logic provides proper initialization and connections for PPC405 clock/power management, resets, PLB cycle control, and OCM interfaces. It also couples user signals between the FPGA fabric and the embedded PPC405 CPU core.

The processor clock connectivity is similar to CLB clock pins. It can connect either to global clock nets or general routing resources. Therefore the processor clock source can come from DCM, CLB, or user package pin.

CPU-FPGA Interfaces

All Processor Block user pins link up with the general FPGA routing resources through the CPU-FPGA interface. Therefore processor signals have the same routability as other non-Processor Block user signals. Longlines and hex lines travel across the Processor Block both vertically and horizontally, allowing signals to route through the Processor Block.

Processor Local Bus (PLB) Interfaces

The PPC405 core accesses high-speed system resources through PLB interfaces on the instruction and data cache controllers. The PLB interfaces provide separate 32-bit address/64-bit data buses for the instruction and data sides.

The cache controllers are both PLB masters. PLB arbiters are implemented in the FPGA fabric and are available as soft IP cores.

Device Control Register (DCR) Bus Interface

The device control register (DCR) bus has 10 bits of address space for components external to the PPC405 core. Using the DCR bus to manage status and configuration registers reduces PLB traffic and improves system integrity. System resources on the DCR bus are protected or isolated from wayward code since the DCR bus is not part of the system memory map.

External Interrupt Controller (EIC) Interface

Two level-sensitive user interrupt pins (critical and non-critical) are available. They can be either driven by user defined logic or Xilinx soft interrupt controller IP core outside the Processor Block.

Clock/Power Management (CPM) Interface

The CPM interface supports several methods of clock distribution and power management. Three modes of operation that reduce power consumption below the normal operational level are available.

Reset Interface

There are three user reset input pins (core, chip, and system) and three user reset output pins for different levels of reset, if required.

Debug Interface

Debugging interfaces on the embedded PPC405 core, consisting of the JTAG and Trace ports, offer access to resources internal to the core and assist in software development. The JTAG port provides basic JTAG chip testing functionality as well as the ability for external debug tools to gain control of the processor for debug purposes. The Trace port furnishes programmers with a mechanism for acquiring instruction execution traces.

The JTAG port is compatible with IEEE Std 1149.1, which defines a test access port (TAP) and Boundary-Scan architecture. Extensions to the JTAG interface provide debuggers with processor control that includes stopping, starting, and stepping the PPC405 core. These extensions are compliant with the IEEE 1149.1 specifications for vendor-specific extensions.

IOB Output Switching Characteristics

Output delays terminating at a pad are specified for LVCMOS25 with 12 mA drive and fast slew rate. For other standards, adjust the delays with the values shown in IOB Output Switching Characteristics Standard Adjustments.

Table 37: **IOB Output Switching Characteristics**

		Speed Grade			
Description	**Symbol**	**-7**	**-6**	**-5**	**Units**
Propagation Delays					
O input to Pad	T_{IOOP}	1.58	1.68	1.85	ns, max
O input to Pad via transparent latch	T_{IOOLP}	1.65	1.82	1.99	ns, max
3-State Delays					
T input to Pad high-impedance(2)	T_{IOTHZ}	1.23	1.35	1.51	ns, max
T input to valid data on Pad	T_{IOTP}	1.51	1.63	1.78	ns, max
T input to Pad high-impedance via transparent latch(2)	$T_{IOTLPHZ}$	1.08	1.22	1.36	ns, max
T input to valid data on Pad via transparent latch	$T_{IOTLPON}$	1.56	1.69	1.85	ns, max
GTS to Pad high-impedance(2)	T_{GTS}	4.11	4.73	5.20	ns, max
Sequential Delays					
Clock CLK to Pad	T_{IOCKP}	1.59	1.76	1.93	ns, max
Clock CLK to Pad high-impedance (synchronous)(2)	T_{IOCKHZ}	1.39	1.55	1.73	ns, max
Clock CLK to valid data on Pad (synchronous)	T_{IOCKON}	1.67	1.82	2.00	ns, max
Setup and Hold Times Before/After Clock CLK					
O input	T_{IOOCK}/T_{IOCKO}	0.23/ 0.12	0.26/ 0.14	0.29/ 0.15	ns, min
OCE input	$T_{IOOCECK}/T_{IOCKOCE}$	0.39/ 0.01	0.44/ 0.01	0.49/ 0.01	ns, min
SR input (OFF)	$T_{IOSRCKO}/T_{IOCKOSR}$	0.52/ 0.00	0.57/ 0.00	0.75/ 0.00	ns, min
3–State Setup Times, T input	T_{IOTCK}/T_{IOCKT}	0.23/ 0.12	0.26/ 0.14	0.29/ 0.15	ns, min
3-State Setup Times, TCE input	$T_{IOTCECK}/T_{IOCKTCE}$	0.39/ 0.01	0.44/ 0.01	0.49/ 0.01	ns, min
3-State Setup Times, SR input (TFF)	$T_{IOSRCKT}/T_{IOCKTSR}$	0.52/ 0.00	0.57/ 0.00	0.75/ 0.00	ns, min
Set/Reset Delays					
Minimum Pulse Width, SR inputs (asynchronous)	T_{RPW}	0.37	0.40	0.45	ns, min
SR input to Pad (asynchronous)	T_{IOSRP}	2.33	2.56	2.83	ns, max
SR input to Pad high-impedance (asynchronous)(2)	T_{IOSRHZ}	1.97	2.16	2.41	ns, max
SR input to valid data on Pad (asynchronous)	T_{IOSRON}	2.24	2.44	2.69	ns, max
GSR to Pad	T_{IOGSRQ}	5.87	6.75	7.43	ns, max

Notes:
1. A Zero “0” Hold Time listing indicates no hold time or a negative hold time. Negative values can not be guaranteed “best-case”, but if a “0” is listed, there is no positive hold time.
2. The 3-state turn-off delays should not be adjusted.

I/O Standard Adjustment Measurement Methodology

Input Delay Measurements

Table 39 shows the test setup parameters used for measuring Input standard adjustments (see Table 36, page 25).

Table 39: **Input Delay Measurement Methodology**

Description	IOSTANDARD Attribute	V_L (1,2)	V_H (1,2)	V_{MEAS} (1,4,5)	V_{REF} (1,3,5)
LVTTL (Low-Voltage Transistor-Transistor Logic)	LVTTL	0	3.3	1.65	–
LVCMOS (Low-Voltage CMOS), 3.3V	LVCMOS33	0	3.3	1.65	–
LVCMOS, 2.5V	LVCMOS25	0	2.5	1.25	–
LVCMOS, 1.8V	LVCMOS18	0	1.8	0.9	–
LVCMOS, 1.5V	LVCMOS15	0	1.5	0.75	–
PCI (Peripheral Component Interface), 33 MHz, 3.3V	PCI33_3	Per PCI Specification			–
PCI, 66 MHz, 3.3V	PCI66_3	Per PCI Specification			–
PCI-X, 133 MHz, 3.3V	PCIX	Per PCI-X Specification			–
GTL (Gunning Transceiver Logic)	GTL	V_{REF} – 0.2	V_{REF} + 0.2	V_{REF}	0.80
GTL Plus	GTLP	V_{REF} – 0.2	V_{REF} + 0.2	V_{REF}	1.0
HSTL (High-Speed Transceiver Logic), Class I & II	HSTL_I, HSTL_II	V_{REF} – 0.5	V_{REF} + 0.5	V_{REF}	0.75
HSTL, Class III & IV	HSTL_III, HSTL_IV	V_{REF} – 0.5	V_{REF} + 0.5	V_{REF}	0.90
HSTL, Class I & II, 1.8V	HSTL_I_18, HSTL_II_18	V_{REF} – 0.5	V_{REF} + 0.5	V_{REF}	0.90
HSTL, Class III & IV, 1.8V	HSTL_III_18, HSTL_IV_18	V_{REF} – 0.5	V_{REF} + 0.5	V_{REF}	1.08
SSTL (Stub Terminated Tnscvr Logic), Class I & II, 2.5V	SSTL2_I, SSTL2_II	V_{REF} – 0.75	V_{REF} + 0.75	V_{REF}	1.25
SSTL, Class I & II, 1.8V	SSTL18_I, SSTL18_II	V_{REF} – 0.5	V_{REF} + 0.5	V_{REF}	0.9
LVDS (Low-Voltage Differential Signaling), 2.5V	LVDS_25	1.2 – 0.125	1.2 + 0.125	1.2	
LVDSEXT (LVDS Extended Mode), 2.5V	LVDSEXT_25	1.2 – 0.125	1.2 + 0.125	1.2	
ULVDS (Ultra LVDS), 2.5V	ULVDS_25	0.6 – 0.125	0.6 + 0.125	0.6	
LDT (HyperTransport), 2.5V	LDT_25	0.6 – 0.125	0.6 + 0.125	0.6	
LVPECL (Low-Voltage Positive Emitter-Coupled Logic), 2.5V	LVPECL_25	1.15 – 0.3	1.15 + 0.3	1.15	

Notes:

1. Input delay measurement methodology parameters for LVDCI and HSLVDCI are the same as for LVCMOS standards of the same voltage. Parameters for all other DCI standards are the same as for the corresponding non-DCI standards.
2. Input waveform switches between V_L and V_H.
3. Measurements are made at typical, minimum, and maximum V_{REF} values. Reported delays reflect worst case of these measurements. V_{REF} values listed are typical. See ***Virtex-II Pro Platform FPGA User Guide*** for min/max specifications.
4. Input voltage level from which measurement starts.
5. Note that this is an input voltage reference that bears no relation to the V_{REF} / V_{MEAS} parameters found in IBIS models and/or noted in Figure 6.

Output Delay Measurements

Output delays are measured using a Tektronix P6245 TDS500/600 probe (< 1 pF) across approximately 4" of FR4 microstrip trace. Standard termination was used for all testing. (See ***Virtex-II Pro Platform FPGA User Guide*** for details.) The propagation delay of the 4" trace is characterized separately and subtracted from the final measurement, and is therefore not included in the generalized test setup shown in Figure 6.

Measurements and test conditions are reflected in the IBIS models except where the IBIS format precludes it. (IBIS models can be found on the web at **http://support.xilinx.com/support/sw_ibis.htm**.) Parameters V_{REF}, R_{REF}, C_{REF}, and V_{MEAS} fully describe the test conditions for each I/O standard. The most accurate prediction of propagation delay in any given application can be obtained through IBIS simulation, using the following method:

1. Simulate the output driver of choice into the generalized test setup, using values from Table 40.
2. Record the time to V_{MEAS}.
3. Simulate the output driver of choice into the actual PCB trace and load, using the appropriate IBIS model or capacitance value to represent the load.
4. Record the time to V_{MEAS}.
5. Compare the results of steps 2 and 4. The increase or decrease in delay should be added to or subtracted from the I/O Output Standard Adjustment value (Table 38) to yield the actual worst-case propagation delay (clock-to-input) of the PCB trace.

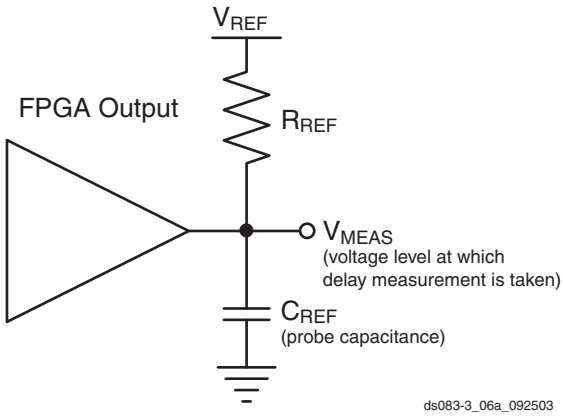

Figure 6: **Generalized Test Setup**

Table 40: **Output Delay Measurement Methodology**

Description	IOSTANDARD Attribute	R_{REF} (Ω)	C_{REF} (1) (pF)	V_{MEAS} (V)	V_{REF} (V)
LVTTL (Low-Voltage Transistor-Transistor Logic)	LVTTL (all)	1M	0	1.65	0
LVCMOS (Low-Voltage CMOS), 3.3V	LVCMOS33	1M	0	1.65	0
LVCMOS, 2.5V	LVCMOS25	1M	0	1.25	0
LVCMOS, 1.8V	LVCMOS18	1M	0	0.9	0
LVCMOS, 1.5V	LVCMOS15	1M	0	0.75	0
PCI (Peripheral Component Interface), 33 MHz, 3.3V	PCI33_3 (rising edge)	25	10 (2)	0.94	0
	PCI33_3 (falling edge)	25	10 (2)	2.03	3.3
PCI, 66 MHz, 3.3V	PCI66_3 (rising edge)	25	10 (2)	0.94	0
	PCI66_3 (falling edge)	25	10 (2)	2.03	3.3
PCI-X, 133 MHz, 3.3V	PCIX (rising edge)	25	10 (3)	0.94	0
	PCIX (falling edge	25	10 (3)	2.03	3.3
GTL (Gunning Transceiver Logic)	GTL	25	0	0.8	1.2
GTL Plus	GTLP	25	0	1.0	1.5
HSTL (High-Speed Transceiver Logic), Class I	HSTL_I	50	0	V_{REF}	0.75
HSTL, Class II	HSTL_II	25	0	V_{REF}	0.75
HSTL, Class III	HSTL_III	50	0	0.9	1.5
HSTL, Class IV	HSTL_IV	25	0	0.9	1.5
HSTL, Class I, 1.8V	HSTL_I_18	50	0	V_{REF}	0.9
HSTL, Class II, 1.8V	HSTL_II_18	25	0	V_{REF}	0.9
HSTL, Class III, 1.8V	HSTL_III_18	50	0	1.1	1.8
HSTL, Class IV, 1.8V	HSTL_IV_18	25	0	1.1	1.8

Miscellaneous Timing Parameters

Table 61: **Miscellaneous Timing Parameters**

Description	Symbol	Constraints F_{CLKIN}	Speed Grade			Units
			-7	-6	-5	
Time Required to Achieve LOCK						
Using DLL outputs(1)	LOCK_DLL:					
	LOCK_DLL_60	> 60MHz	20.00	20.00	20.00	us
	LOCK_DLL_50_60	50 - 60 MHz	25.00	25.00	25.00	us
	LOCK_DLL_40_50	40 - 50 MHz	50.00	50.00	50.00	us
	LOCK_DLL_30_40	30 - 40 MHz	90.00	90.00	90.00	us
	LOCK_DLL_24_30	24 - 30 MHz	120.00	120.00	120.00	us
Using CLKFX outputs	LOCK_FX_MIN		10.00	10.00	10.00	ms
	LOCK_FX_MAX		10.00	10.00	10.00	ms
Additional lock time with fine phase shifting	LOCK_DLL_FINE_SHIFT		50.00	50.00	50.00	us
Fine Phase Shifting						
Absolute shifting range	FINE_SHIFT_RANGE		10.00	10.00	10.00	ns
Delay Lines						
Tap delay resolution	DCM_TAP_MIN		30.00	30.00	30.00	ps
	DCM_TAP_MAX		50.00	50.00	50.00	ps

Notes:
1. “DLL outputs” is used here to describe the outputs: CLK0, CLK90, CLK180, CLK270, CLK2X, CLK2X180, and CLKDV.

Frequency Synthesis

Table 62: **Frequency Synthesis**

Attribute	Min	Max
CLKFX_MULTIPLY	2	32
CLKFX_DIVIDE	1	32

Parameter Cross-Reference

Table 63: **Parameter Cross-Reference**

Libraries Guide	Data Sheet
DLL_CLKOUT_{MIN|MAX}_LF	CLKOUT_FREQ_{1X|2X|DV}_LF
DFS_CLKOUT_{MIN|MAX}_LF	CLKOUT_FREQ_FX_LF
DLL_CLKIN_{MIN|MAX}_LF	CLKIN_FREQ_DLL_LF
DFS_CLKIN_{MIN|MAX}_LF	CLKIN_FREQ_FX_LF
DLL_CLKOUT_{MIN|MAX}_HF	CLKOUT_FREQ_{1X|DV}_HF
DFS_CLKOUT_{MIN|MAX}_HF	CLKOUT_FREQ_FX_HF
DLL_CLKIN_{MIN|MAX}_HF	CLKIN_FREQ_DLL_HF
DFS_CLKIN_{MIN|MAX}_HF	CLKIN_FREQ_FX_HF

Table 5: **FG256/FGG256 — XC2VP2 and XC2VP4**

Bank	Pin Description	Pin Number
7	IO_L85N_7	G2
7	IO_L06P_7	G3
7	IO_L06N_7	G4
7	IO_L04P_7	F1
7	IO_L04N_7/VREF_7	F2
7	IO_L03P_7	F3
7	IO_L03N_7	F4
7	IO_L02P_7	F5
7	IO_L02N_7	E4
7	IO_L01P_7/VRN_7	E2
7	IO_L01N_7/VRP_7	E3
0	VCCO_0	F8
0	VCCO_0	F7
0	VCCO_0	E8
1	VCCO_1	F9
1	VCCO_1	F10
1	VCCO_1	E9
2	VCCO_2	H12
2	VCCO_2	H11
2	VCCO_2	G11
3	VCCO_3	K11
3	VCCO_3	J12
3	VCCO_3	J11
4	VCCO_4	M9
4	VCCO_4	L9
4	VCCO_4	L10
5	VCCO_5	M8
5	VCCO_5	L8
5	VCCO_5	L7
6	VCCO_6	K6
6	VCCO_6	J6
6	VCCO_6	J5
7	VCCO_7	H6
7	VCCO_7	H5

Table 7: **FG676/FGG676 — XC2VP20, XC2VP30, and XC2VP40**

Bank	Pin Description	Pin Number	No Connects		
			XC2VP20	XC2VP30	XC2VP40
N/A	VTTXPAD4	B4			
N/A	TXNPAD4	A4			
N/A	TXPPAD4	A5			
N/A	GNDA4	C6			
N/A	RXPPAD4	A6			
N/A	RXNPAD4	A7			
N/A	VTRXPAD4	B6			
N/A	AVCCAUXRX4	B7			
N/A	AVCCAUXTX6	B10			
N/A	VTTXPAD6	B9			
N/A	TXNPAD6	A9			
N/A	TXPPAD6	A10			
N/A	GNDA6	C11			
N/A	RXPPAD6	A11			
N/A	RXNPAD6	A12			
N/A	VTRXPAD6	B11			
N/A	AVCCAUXRX6	B12			
N/A	AVCCAUXTX7	B16			
N/A	VTTXPAD7	B15			
N/A	TXNPAD7	A15			
N/A	TXPPAD7	A16			
N/A	GNDA7	C16			
N/A	RXPPAD7	A17			
N/A	RXNPAD7	A18			
N/A	VTRXPAD7	B17			
N/A	AVCCAUXRX7	B18			
N/A	AVCCAUXTX9	B21			
N/A	VTTXPAD9	B20			
N/A	TXNPAD9	A20			
N/A	TXPPAD9	A21			
N/A	GNDA9	C21			
N/A	RXPPAD9	A22			
N/A	RXNPAD9	A23			
N/A	VTRXPAD9	B22			
N/A	AVCCAUXRX9	B23			

Table 8: **FF672 — XC2VP2, XC2VP4, and XC2VP7**

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
7	IO_L44P_7	G24	NC		
7	IO_L44N_7	G23	NC		
7	IO_L43P_7	G22	NC		
7	IO_L43N_7	G21	NC		
7	IO_L42P_7	F25	NC	NC	NC
7	IO_L42N_7	F24	NC	NC	NC
7	IO_L40P_7	F23	NC	NC	NC
7	IO_L40N_7/VREF_7	F22	NC	NC	NC
7	IO_L06P_7	E26			
7	IO_L06N_7	E25			
7	IO_L05P_7	E24			
7	IO_L05N_7	E23			
7	IO_L04P_7	D26			
7	IO_L04N_7/VREF_7	D25			
7	IO_L03P_7	C26			
7	IO_L03N_7	C25			
7	IO_L02P_7	B26			
7	IO_L02N_7	A25			
7	IO_L01P_7/VRN_7	D24			
7	IO_L01N_7/VRP_7	C23			
0	VCCO_0	C17			
0	VCCO_0	C20			
0	VCCO_0	H17			
0	VCCO_0	H18			
0	VCCO_0	J14			
0	VCCO_0	J15			
0	VCCO_0	J16			
1	VCCO_1	C7			
1	VCCO_1	H9			
1	VCCO_1	C10			
1	VCCO_1	H10			
1	VCCO_1	J11			
1	VCCO_1	J12			
1	VCCO_1	J13			
2	VCCO_2	G2			
2	VCCO_2	J8			

Table 9: **FF896 — XC2VP7, XC2VP20, XC2VPX20, and XC2VP30**

Bank	Pin Description		Pin Number	No Connects		
	Virtex-II Pro devices	XC2VPX20 (if Different)		XC2VP7	XC2VP20, XC2VPX20	XC2VP30
4	VCCO_4		AA11			
4	VCCO_4		AA10			
5	VCCO_5		AB21			
5	VCCO_5		AB20			
5	VCCO_5		AB19			
5	VCCO_5		AB18			
5	VCCO_5		AA21			
5	VCCO_5		AA20			
5	VCCO_5		AA19			
5	VCCO_5		AA18			
5	VCCO_5		AA17			
5	VCCO_5		AA16			
6	VCCO_6		AB22			
6	VCCO_6		AA22			
6	VCCO_6		Y22			
6	VCCO_6		Y21			
6	VCCO_6		W22			
6	VCCO_6		W21			
6	VCCO_6		V22			
6	VCCO_6		V21			
6	VCCO_6		U21			
6	VCCO_6		T21			
7	VCCO_7		R21			
7	VCCO_7		P21			
7	VCCO_7		N22			
7	VCCO_7		N21			
7	VCCO_7		M22			
7	VCCO_7		M21			
7	VCCO_7		L22			
7	VCCO_7		L21			
7	VCCO_7		K22			
7	VCCO_7		J22			
N/A	CCLK		AC7			
N/A	PROG_B		G24			
N/A	DONE		AC8			

Table 9: **FF896 — XC2VP7, XC2VP20, XC2VPX20, and XC2VP30**

Bank	Pin Description		Pin Number	No Connects		
	Virtex-II Pro devices	XC2VPX20 (if Different)		XC2VP7	XC2VP20, XC2VPX20	XC2VP30
N/A	VCCINT		Y13			
N/A	VCCINT		Y12			
N/A	VCCINT		W20			
N/A	VCCINT		W11			
N/A	VCCINT		V20			
N/A	VCCINT		V11			
N/A	VCCINT		U20			
N/A	VCCINT		U11			
N/A	VCCINT		T20			
N/A	VCCINT		T11			
N/A	VCCINT		R20			
N/A	VCCINT		R11			
N/A	VCCINT		P20			
N/A	VCCINT		P11			
N/A	VCCINT		N20			
N/A	VCCINT		N11			
N/A	VCCINT		M20			
N/A	VCCINT		M11			
N/A	VCCINT		L19			
N/A	VCCINT		L18			
N/A	VCCINT		L17			
N/A	VCCINT		L16			
N/A	VCCINT		L15			
N/A	VCCINT		L14			
N/A	VCCINT		L13			
N/A	VCCINT		L12			
N/A	GND		AK22			
N/A	GND		AK9			
N/A	GND		AJ29			
N/A	GND		AJ2			
N/A	GND		AH28			
N/A	GND		AH17			
N/A	GND		AH14			
N/A	GND		AH3			
N/A	GND		AG27			
N/A	GND		AG22			

Table 12: **FF1517 — XC2VP50 and XC2VP70**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
5	IO_L57N_5/VREF_5	AT23		
5	IO_L57P_5	AU23		
5	IO_L56N_5	AJ22		
5	IO_L56P_5	AK22		
5	IO_L55N_5	AN23		
5	IO_L55P_5	AP24		
5	IO_L54N_5	AL23		
5	IO_L54P_5	AM23		
5	IO_L53_5/No_Pair	AH23		
5	IO_L50_5/No_Pair	AG23		
5	IO_L49N_5	AR24		
5	IO_L49P_5	AR25		
5	IO_L48N_5	AL24		
5	IO_L48P_5	AM24		
5	IO_L47N_5	AH22		
5	IO_L47P_5	AJ23		
5	IO_L46N_5	AT25		
5	IO_L46P_5	AU25		
5	IO_L45N_5/VREF_5	AN25		
5	IO_L45P_5	AP25		
5	IO_L44N_5	AH24		
5	IO_L44P_5	AH25		
5	IO_L43N_5	AL25		
5	IO_L43P_5	AM25		
5	IO_L39N_5	AT26		
5	IO_L39P_5	AU26		
5	IO_L38N_5	AK24		
5	IO_L38P_5	AK25		
5	IO_L37N_5	AP26		
5	IO_L37P_5	AR26		
5	IO_L36N_5/VREF_5	AM26	NC	
5	IO_L36P_5	AN26	NC	
5	IO_L35N_5	AJ25	NC	
5	IO_L35P_5	AJ26	NC	
5	IO_L34N_5	AR27	NC	
5	IO_L34P_5	AT27	NC	
5	IO_L30N_5	AN27	NC	
5	IO_L30P_5	AP28	NC	

Table 12: **FF1517 — XC2VP50 and XC2VP70**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
N/A	M2	AJ29		
N/A	TCK	E8		
N/A	TDI	L30		
N/A	TDO	L10		
N/A	TMS	F9		
N/A	PWRDWN_B	AP9		
N/A	HSWAP_EN	E32		
N/A	RSVD	D8		
N/A	VBATT	L11		
N/A	DXP	L29		
N/A	DXN	F31		
N/A	AVCCAUXTX2	B35		
N/A	VTTXPAD2	B36		
N/A	TXNPAD2	A36		
N/A	TXPPAD2	A35		
N/A	GNDA2	C34		
N/A	RXPPAD2	A34		
N/A	RXNPAD2	A33		
N/A	VTRXPAD2	B34		
N/A	AVCCAUXRX2	B33		
N/A	AVCCAUXTX4	B31		
N/A	VTTXPAD4	B32		
N/A	TXNPAD4	A32		
N/A	TXPPAD4	A31		
N/A	GNDA4	C31		
N/A	RXPPAD4	A30		
N/A	RXNPAD4	A29		
N/A	VTRXPAD4	B30		
N/A	AVCCAUXRX4	B29		
N/A	AVCCAUXTX5	B27		
N/A	VTTXPAD5	B28		
N/A	TXNPAD5	A28		
N/A	TXPPAD5	A27		
N/A	GNDA5	C27		
N/A	RXPPAD5	A26		
N/A	RXNPAD5	A25		
N/A	VTRXPAD5	B26		
N/A	AVCCAUXRX5	B25		

Table 13: **FF1704 — XC2VP70, XC2VPX70, and XC2VP100**

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
2	IO_L26P_2		N12		
2	IO_L27N_2		P9		
2	IO_L27P_2		P10		
2	IO_L28N_2/VREF_2		P7		
2	IO_L28P_2		P8		
2	IO_L29N_2		P11		
2	IO_L29P_2		P12		
2	IO_L30N_2		P5		
2	IO_L30P_2		P6		
2	IO_L31N_2		P1		
2	IO_L31P_2		P2		
2	IO_L32N_2		R9		
2	IO_L32P_2		R10		
2	IO_L33N_2		R5		
2	IO_L33P_2		R6		
2	IO_L34N_2/VREF_2		P3		
2	IO_L34P_2		R3		
2	IO_L35N_2		R1		
2	IO_L35P_2		R2		
2	IO_L36N_2		R11		
2	IO_L36P_2		R12		
2	IO_L37N_2		T6		
2	IO_L37P_2		T7		
2	IO_L38N_2		T8		
2	IO_L38P_2		R8		
2	IO_L39N_2		T4		
2	IO_L39P_2		T5		
2	IO_L40N_2/VREF_2		T2		
2	IO_L40P_2		T3		
2	IO_L41N_2		T10		
2	IO_L41P_2		T11		
2	IO_L42N_2		U7		
2	IO_L42P_2		U8		
2	IO_L43N_2		U5		
2	IO_L43P_2		U6		
2	IO_L44N_2		U9		

Table 13: **FF1704 — XC2VP70, XC2VPX70, and XC2VP100**

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
7	IO_L09P_7		K36		
7	IO_L09N_7		K35		
7	IO_L08P_7		K38		
7	IO_L08N_7		K37		
7	IO_L07P_7		L33		
7	IO_L07N_7		K34		
7	IO_L84P_7		J41		
7	IO_L84N_7		J42		
7	IO_L83P_7		J39		
7	IO_L83N_7		J38		
7	IO_L82P_7		J36		
7	IO_L82N_7/VREF_7		J37		
7	IO_L81P_7		J35		
7	IO_L81N_7		H36		
7	IO_L80P_7		H41		
7	IO_L80N_7		H40		
7	IO_L79P_7		H38		
7	IO_L79N_7		H39		
7	IO_L78P_7		H37		
7	IO_L78N_7		G38		
7	IO_L77P_7		G42		
7	IO_L77N_7		G41		
7	IO_L76P_7		G39		
7	IO_L76N_7/VREF_7		G40		
7	IO_L75P_7		F41		
7	IO_L75N_7		F42		
7	IO_L74P_7		F40		
7	IO_L74N_7		F39		
7	IO_L73P_7		E41		
7	IO_L73N_7		E42		
7	IO_L06P_7		D41		
7	IO_L06N_7		D42		
7	IO_L05P_7		E40		
7	IO_L05N_7		D40		
7	IO_L04P_7		F36		
7	IO_L04N_7/VREF_7		G37		

Table 13: **FF1704 — XC2VP70, XC2VPX70, and XC2VP100**

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
N/A	TXPPAD7		A20		
N/A	GNDA7		C21		
N/A	RXPPAD7		A19		
N/A	RXNPAD7		A18		
N/A	VTRXPAD7		B19		
N/A	AVCCAUXRX7		B18		
N/A	AVCCAUXTX8		B16		
N/A	VTTXPAD8		B17		
N/A	TXNPAD8		A17		
N/A	TXPPAD8		A16		
N/A	GNDA8		C16		
N/A	RXPPAD8		A15		
N/A	RXNPAD8		A14		
N/A	VTRXPAD8		B15		
N/A	AVCCAUXRX8		B14		
N/A	AVCCAUXTX9		B12		
N/A	VTTXPAD9		B13		
N/A	TXNPAD9		A13		
N/A	TXPPAD9		A12		
N/A	GNDA9		C12		
N/A	RXPPAD9		A11		
N/A	RXNPAD9		A10		
N/A	VTRXPAD9		B11		
N/A	AVCCAUXRX9		B10		
N/A	AVCCAUXTX10		B8		
N/A	VTTXPAD10		B9		
N/A	TXNPAD10		A9		
N/A	TXPPAD10		A8		
N/A	GNDA10		C8		
N/A	RXPPAD10		A7		
N/A	RXNPAD10		A6		
N/A	VTRXPAD10		B7		
N/A	AVCCAUXRX10		B6		
N/A	AVCCAUXTX11		B4		
N/A	VTTXPAD11		B5		
N/A	TXNPAD11		A5		

Table 13: **FF1704 — XC2VP70, XC2VPX70, and XC2VP100**

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
N/A	RXPPAD21		BB31		
N/A	GNDA21		AY31		
N/A	TXPPAD21		BB32		
N/A	TXNPAD21		BB33		
N/A	VTTXPAD21		BA33		
N/A	AVCCAUXTX21		BA32		
N/A	AVCCAUXRX22		BA34		
N/A	VTRXPAD22		BA35		
N/A	RXNPAD22		BB34		
N/A	RXPPAD22		BB35		
N/A	GNDA22		AY35		
N/A	TXPPAD22		BB36		
N/A	TXNPAD22		BB37		
N/A	VTTXPAD22		BA37		
N/A	AVCCAUXTX22		BA36		
N/A	AVCCAUXRX23		BA38		
N/A	VTRXPAD23		BA39		
N/A	RXNPAD23		BB38		
N/A	RXPPAD23		BB39		
N/A	GNDA23		AY39		
N/A	TXPPAD23		BB40		
N/A	TXNPAD23		BB41		
N/A	VTTXPAD23		BA41		
N/A	AVCCAUXTX23		BA40		
N/A	VCCINT		AB27		
N/A	VCCINT		AB16		
N/A	VCCINT		AC27		
N/A	VCCINT		AC16		
N/A	VCCINT		AD27		
N/A	VCCINT		AD16		
N/A	VCCINT		AE27		
N/A	VCCINT		AE16		
N/A	VCCINT		AF27		
N/A	VCCINT		AF26		
N/A	VCCINT		AF17		

Table 14: **FF1696 — XC2VP100**

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
0	IO_L67P_0	J22	
0	IO_L68N_0	K23	
0	IO_L68P_0	L23	
0	IO_L69N_0	F22	
0	IO_L69P_0/VREF_0	G22	
0	IO_L73N_0	D22	
0	IO_L73P_0	E22	
0	IO_L74N_0/GCLK7P	K22	
0	IO_L74P_0/GCLK6S	L22	
0	IO_L75N_0/GCLK5P	B22	
0	IO_L75P_0/GCLK4S	C22	
1	IO_L75N_1/GCLK3P	C21	
1	IO_L75P_1/GCLK2S	B21	
1	IO_L74N_1/GCLK1P	L21	
1	IO_L74P_1/GCLK0S	K21	
1	IO_L73N_1	E21	
1	IO_L73P_1	D21	
1	IO_L69N_1/VREF_1	G21	
1	IO_L69P_1	F21	
1	IO_L68N_1	L20	
1	IO_L68P_1	K20	
1	IO_L67N_1	J21	
1	IO_L67P_1	H21	
1	IO_L66N_1/VREF_1	C20	
1	IO_L66P_1	B20	
1	IO_L65N_1	M20	
1	IO_L65P_1	M21	
1	IO_L64N_1	G20	
1	IO_L64P_1	F20	
1	IO_L60N_1	B19	
1	IO_L60P_1	A19	
1	IO_L59N_1	K19	
1	IO_L59P_1	J19	
1	IO_L58N_1	D19	
1	IO_L58P_1	D20	
1	IO_L57N_1/VREF_1	F19	

Table 14: **FF1696 — XC2VP100**

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
4	IO_L39N_4	AM16	
4	IO_L39P_4	AL16	
4	IO_L43N_4	AR17	
4	IO_L43P_4	AR16	
4	IO_L44N_4	AV16	
4	IO_L44P_4	AU16	
4	IO_L45N_4	AP16	
4	IO_L45P_4/VREF_4	AN16	
4	IO_L10N_4	AW17	NC
4	IO_L10P_4	AW16	NC
4	IO_L11N_4	BB16	NC
4	IO_L11P_4	BA16	NC
4	IO_L12N_4	AL18	NC
4	IO_L12P_4	AL17	NC
4	IO_L16N_4	AU17	NC
4	IO_L16P_4	AT17	NC
4	IO_L18N_4	BA17	NC
4	IO_L18P_4/VREF_4	AY17	NC
4	IO_L46N_4	AT19	
4	IO_L46P_4	AT18	
4	IO_L47N_4	AN17	
4	IO_L47P_4	AM17	
4	IO_L48N_4	AV18	
4	IO_L48P_4	AU18	
4	IO_L49N_4	AY19	
4	IO_L49P_4	AY18	
4	IO_L50_4/No_Pair	AM19	
4	IO_L53_4/No_Pair	AM18	
4	IO_L54N_4	BB18	
4	IO_L54P_4	BA18	
4	IO_L55N_4	AR20	
4	IO_L55P_4	AR19	
4	IO_L56N_4	AP18	
4	IO_L56P_4	AN18	
4	IO_L57N_4	AV19	
4	IO_L57P_4/VREF_4	AU19	
4	IO_L58N_4	AW20	

Table 14: **FF1696 — XC2VP100**

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
2	VCCO_2	F4	
1	VCCO_1	R21	
1	VCCO_1	P21	
1	VCCO_1	R20	
1	VCCO_1	P20	
1	VCCO_1	R19	
1	VCCO_1	P19	
1	VCCO_1	R18	
1	VCCO_1	P18	
1	VCCO_1	H18	
1	VCCO_1	D18	
1	VCCO_1	P17	
1	VCCO_1	H14	
1	VCCO_1	D14	
1	VCCO_1	M13	
1	VCCO_1	D10	
0	VCCO_0	D33	
0	VCCO_0	M30	
0	VCCO_0	H29	
0	VCCO_0	D29	
0	VCCO_0	P26	
0	VCCO_0	R25	
0	VCCO_0	P25	
0	VCCO_0	H25	
0	VCCO_0	D25	
0	VCCO_0	R24	
0	VCCO_0	P24	
0	VCCO_0	R23	
0	VCCO_0	P23	
0	VCCO_0	R22	
0	VCCO_0	P22	
N/A	CCLK	AM10	
N/A	PROG_B	J33	
N/A	DONE	AN10	
N/A	M0	AP33	
N/A	M1	AN33	